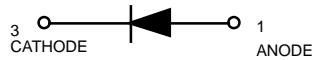


# High Voltage Switching Diode


**BAS21LT1**

CASE 318-08, STYLE 8  
SOT-23 (TO-236AB)

**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	$V_R$	250	Vdc
Peak Forward Current	$I_F$	200	mAdc
Peak Forward Surge Current	$I_{F(surge)}$	625	mAdc

**DEVICE MARKING**

BAS21LT1 = JS

**THERMAL CHARACTERISTICS**

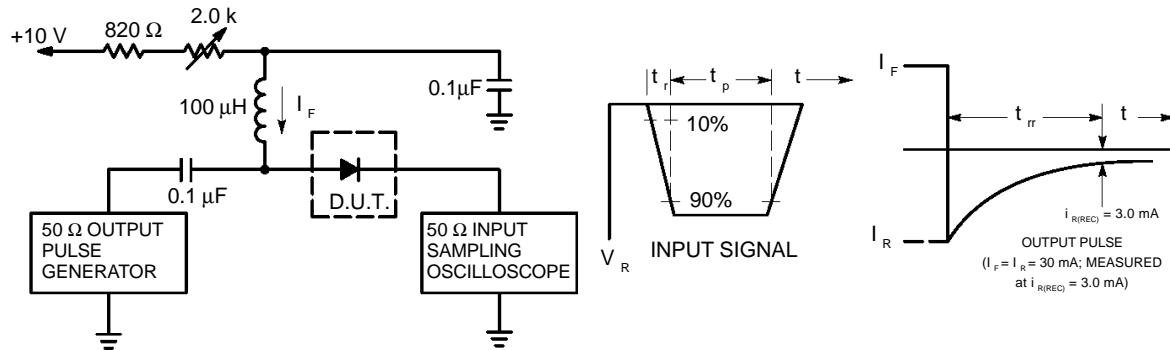
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (1)	$P_D$	225	mW
$T_A = 25^\circ\text{C}$		1.8	mW/ $^\circ\text{C}$
Derate above $25^\circ\text{C}$			
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation	$P_D$	300	mW
Alumina Substrate, (2) $T_A = 25^\circ\text{C}$		2.4	mW/ $^\circ\text{C}$
Derate above $25^\circ\text{C}$			
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Reverse Voltage Leakage Current ( $V_R = 200\text{Vdc}$ )	$I_R$	—	1.0	$\mu\text{Adc}$
( $V_R = 200\text{Vdc}, T_J = 150^\circ\text{C}$ )		—	100	
Reverse Breakdown Voltage ( $I_{BR} = 100 \mu\text{Adc}$ )	$V_{(BR)}$	250	—	Vdc
Forward Voltage ( $I_F = 100 \text{ mAdc}$ )	$V_F$	—	1000	mV
( $I_F = 200 \text{ mAdc}$ )		—	1250	
Diode Capacitance ( $V_R = 0, f = 1.0 \text{ MHz}$ )	$C_D$	—	5.0	pF
Reverse Recovery Time ( $I_F = I_R = 30\text{mAdc}, R_L = 100 \Omega$ )	$t_{rr}$	—	50	ns

1. FR-5 = 1.0 x 0.75 x 0.062 in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

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Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current ( $I_F$ ) of 30 mA.

2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 30 mA.

3.  $t_p \gg t_{rr}$

**Figure 1. Recovery Time Equivalent Test Circuit**